

To our customers,

Old Company Name in Catalogs and Other Documents

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Renesas Electronics website: <http://www.renesas.com>

April 1st, 2010
Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (<http://www.renesas.com>)

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MOS FIELD EFFECT TRANSISTOR NP80N04MDG, NP80N04NDG, NP80N04PDG

SWITCHING N-CHANNEL POWER MOS FET

DESCRIPTION

The NP80N04MDG, NP80N04NDG, and NP80N04PDG are N-channel MOS Field Effect Transistors designed for high current switching applications.

ORDERING INFORMATION

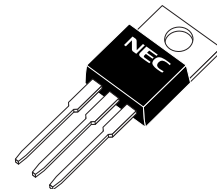
PART NUMBER	LEAD PLATING	PACKING	PACKAGE
NP80N04MDG-S18-AY ^{Note}	Pure Sn (Tin)	Tube	TO-220 (MP-25K) typ. 1.9 g
NP80N04NDG-S18-AY ^{Note}		50 p/tube	TO-262 (MP-25SK) typ. 1.8 g
NP80N04PDG-E1B-AY ^{Note}		Tape	TO-263 (MP-25ZP) typ. 1.5 g
NP80N04PDG-E2B-AY ^{Note}		1000 p/reel	

Note Pb-free (This product does not contain Pb in the external electrode.)

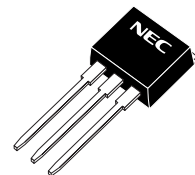
FEATURES

- Logic level
- Super low on-state resistance
 - NP80N04MDG, NP80N04NDG
 - $R_{DS(on)1} = 4.8 \text{ m}\Omega \text{ MAX. (} V_{GS} = 10 \text{ V, } I_D = 40 \text{ A)}$
 - $R_{DS(on)2} = 9.0 \text{ m}\Omega \text{ MAX. (} V_{GS} = 4.5 \text{ V, } I_D = 35 \text{ A)}$
 - NP80N04PDG
 - $R_{DS(on)1} = 4.5 \text{ m}\Omega \text{ MAX. (} V_{GS} = 10 \text{ V, } I_D = 40 \text{ A)}$
 - $R_{DS(on)2} = 8.7 \text{ m}\Omega \text{ MAX. (} V_{GS} = 4.5 \text{ V, } I_D = 35 \text{ A)}$
- High current rating
 - $I_{D(DC)} = \pm 80 \text{ A}$
- Low input capacitance
 - $C_{iss} = 4600 \text{ pF TYP.}$
- Designed for automotive application and AEC-Q101 qualified

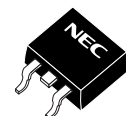
(TO-220)



(TO-262)



(TO-263)



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ABSOLUTE MAXIMUM RATINGS (T_A = 25°C)

Drain to Source Voltage (V _{GS} = 0 V)	V _{DSS}	40	V
Gate to Source Voltage (V _{bs} = 0 V)	V _{GSS}	±20	V
Drain Current (DC) (T _C = 25°C)	I _{D(DC)}	±80	A
Drain Current (pulse) ^{Note1}	I _{D(pulse)}	±300	A
Total Power Dissipation (T _C = 25°C)	P _{T1}	115	W
Total Power Dissipation (T _A = 25°C)	P _{T2}	1.8	W
Channel Temperature	T _{ch}	175	°C
Storage Temperature	T _{stg}	-55 to +175	°C
Repetitive Avalanche Current ^{Note2}	I _{AR}	37	A
Repetitive Avalanche Energy ^{Note2}	E _{AR}	137	mJ

Notes 1. PW ≤ 10 μs, Duty Cycle ≤ 1%

2. T_{ch} ≤ 150°C, R_G = 25 Ω

THERMAL RESISTANCE

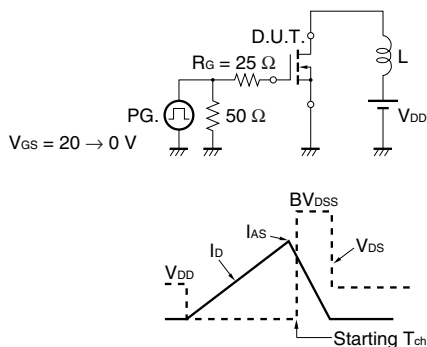
Channel to Case Thermal Resistance	R _{th(ch-C)}	1.30	°C/W
Channel to Ambient Thermal Resistance	R _{th(ch-A)}	83.3	°C/W

ELECTRICAL CHARACTERISTICS (T_A = 25°C)

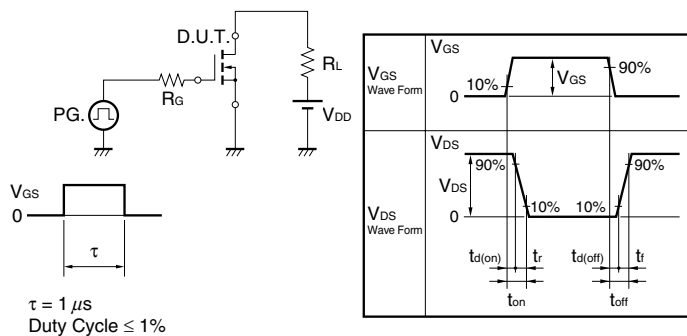
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V			1	μA
Gate Leakage Current	I _{GSS}	V _{GS} = ±20 V, V _{DS} = 0 V			±100	nA
Gate to Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	1.4		2.5	V
Forward Transfer Admittance ^{Note}	y _{fs}	V _{DS} = 5 V, I _D = 35 A	25	63		S
Drain to Source On-state Resistance ^{Note}	R _{Ds(on)1}	V _{GS} = 10 V, I _D = 40 A NP80N04MDG, NP80N04NDG		3.7	4.8	mΩ
		V _{GS} = 10 V, I _D = 40 A NP80N04PDG		3.2	4.5	mΩ
	R _{Ds(on)2}	V _{GS} = 4.5 V, I _D = 35 A NP80N04MDG, NP80N04NDG		4.8	9.0	mΩ
		V _{GS} = 4.5 V, I _D = 35 A NP80N04PDG		4.3	8.7	mΩ
Input Capacitance	C _{iss}	V _{DS} = 25 V,		4600	6900	pF
Output Capacitance	C _{oss}	V _{GS} = 0 V,		480	720	pF
Reverse Transfer Capacitance	C _{rss}	f = 1 MHz		310	560	pF
Turn-on Delay Time	t _{d(on)}	V _{DD} = 20 V, I _D = 40 A,		17	37	ns
Rise Time	t _r	V _{GS} = 10 V,		18	45	ns
Turn-off Delay Time	t _{d(off)}	R _G = 0 Ω		74	148	ns
Fall Time	t _f			8	20	ns
Total Gate Charge	Q _G	V _{DD} = 32 V,		90	135	nC
Gate to Source Charge	Q _{GS}	V _{GS} = 10 V,		13		nC
Gate to Drain Charge	Q _{GD}	I _D = 80 A		26		nC
Body Diode Forward Voltage ^{Note}	V _{F(S-D)}	I _F = 80 A, V _{GS} = 0 V		0.94	1.5	V
Reverse Recovery Time	t _{rr}	I _F = 80 A, V _{GS} = 0 V,		39		ns
Reverse Recovery Charge	Q _{rr}	di/dt = 100 A/μs		39		nC

Note Pulsed test

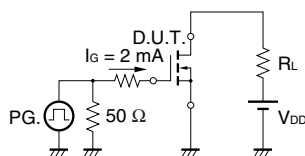
TEST CIRCUIT 1 AVALANCHE CAPABILITY



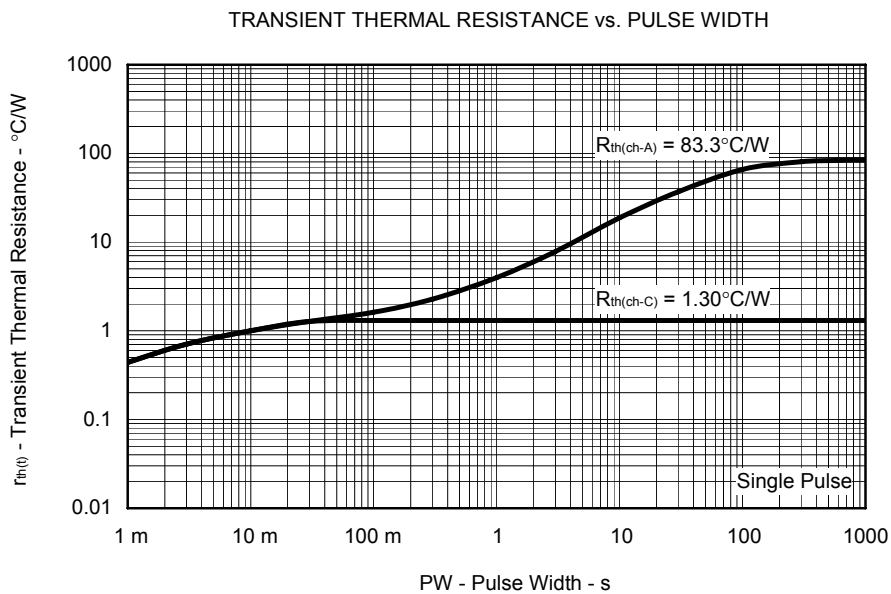
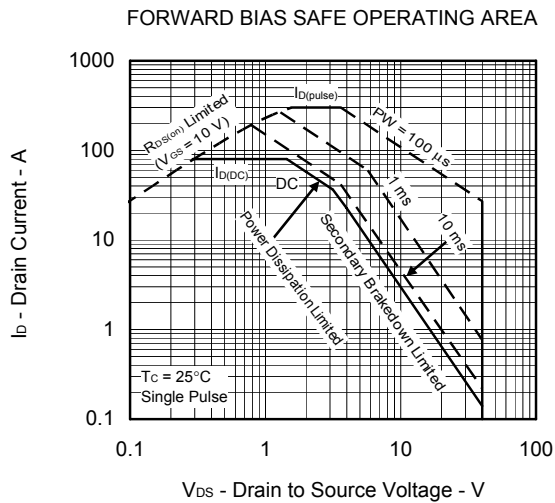
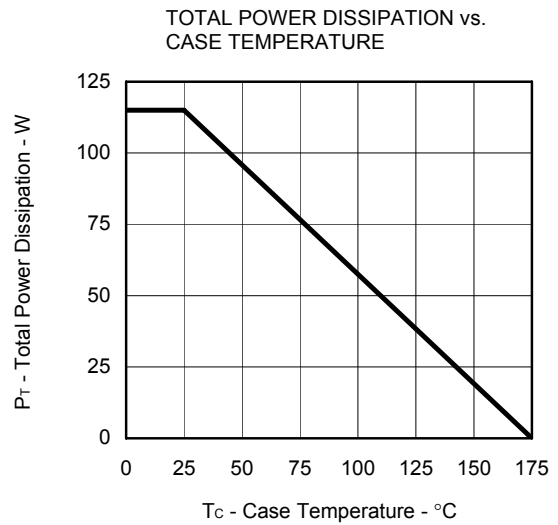
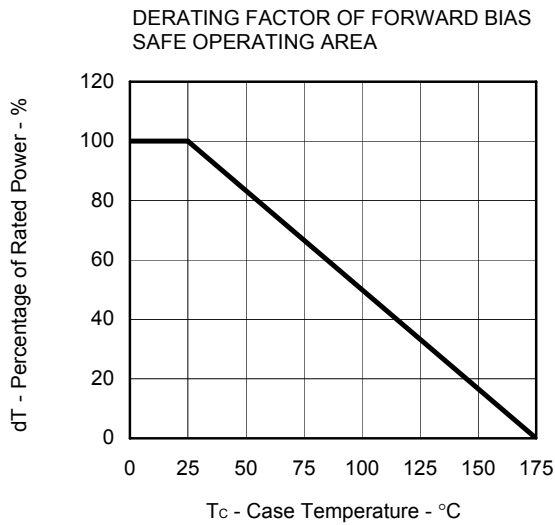
TEST CIRCUIT 2 SWITCHING TIME



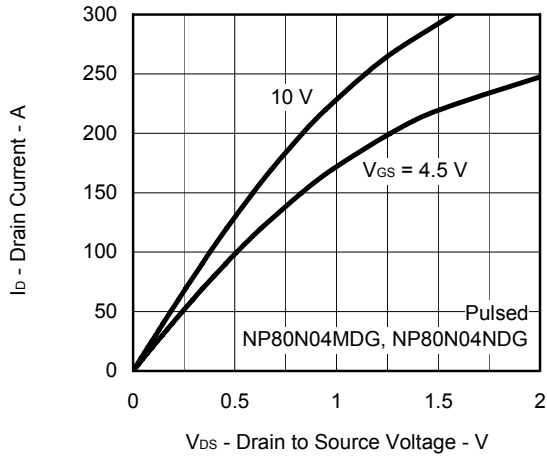
TEST CIRCUIT 3 GATE CHARGE



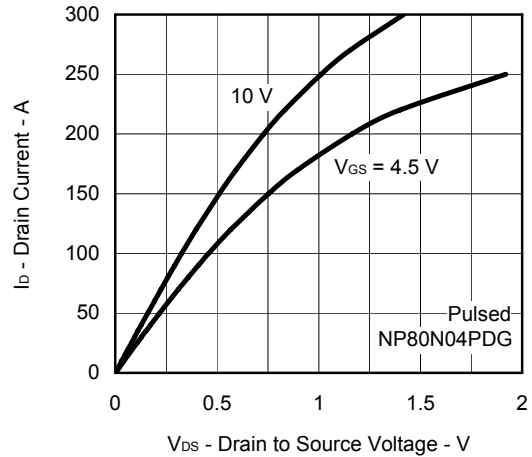
TYPICAL CHARACTERISTICS (T_A = 25°C)



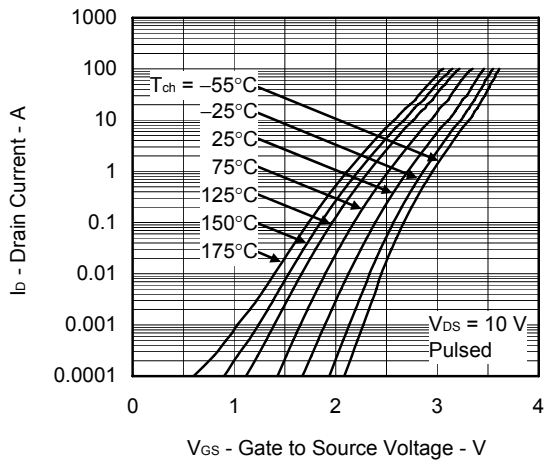
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



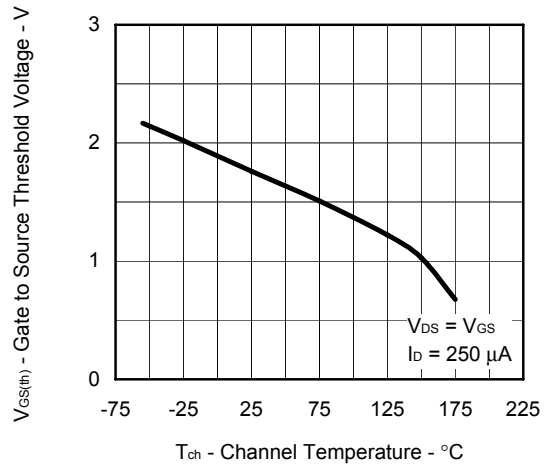
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



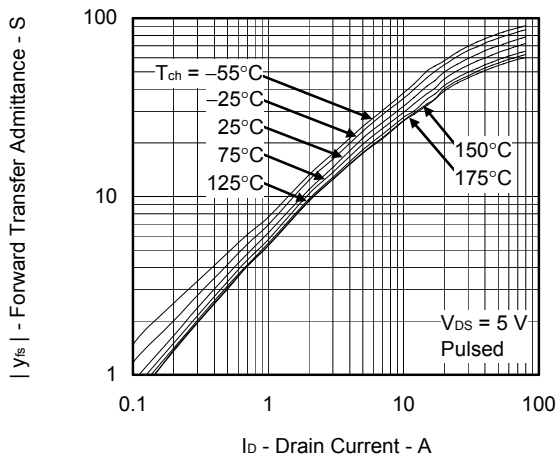
FORWARD TRANSFER CHARACTERISTICS

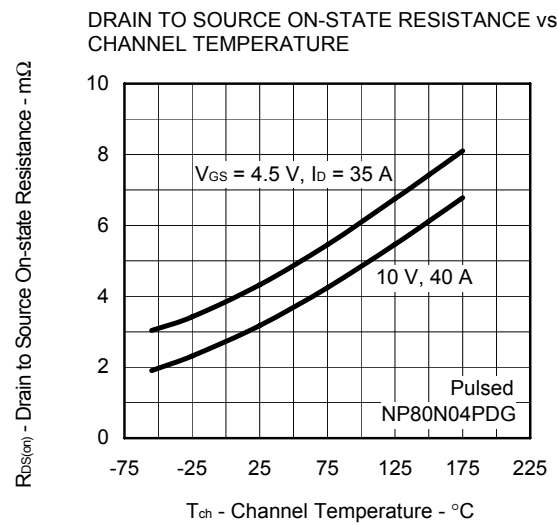
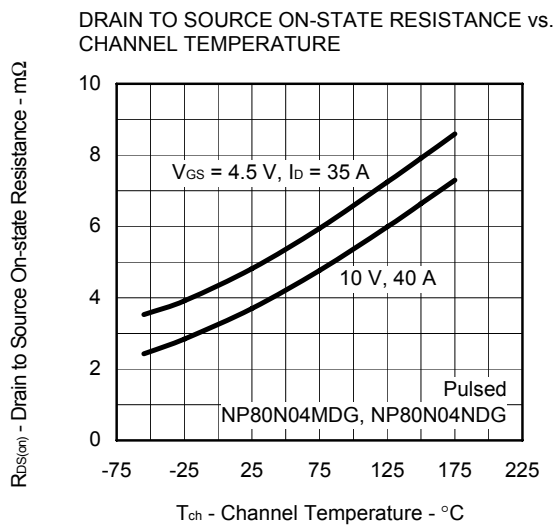
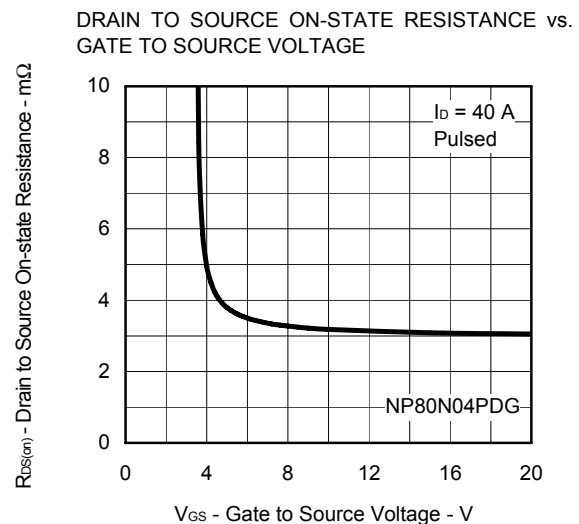
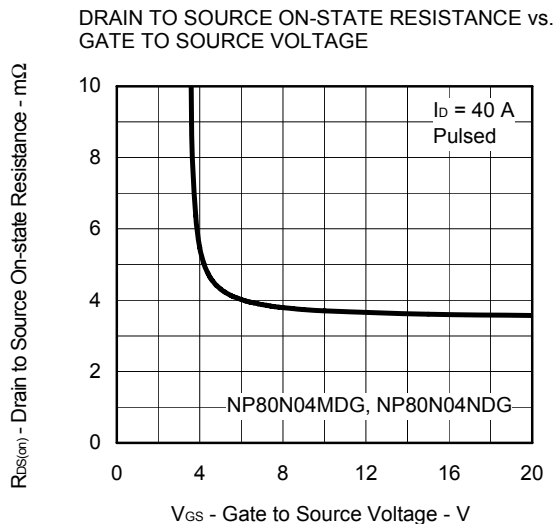
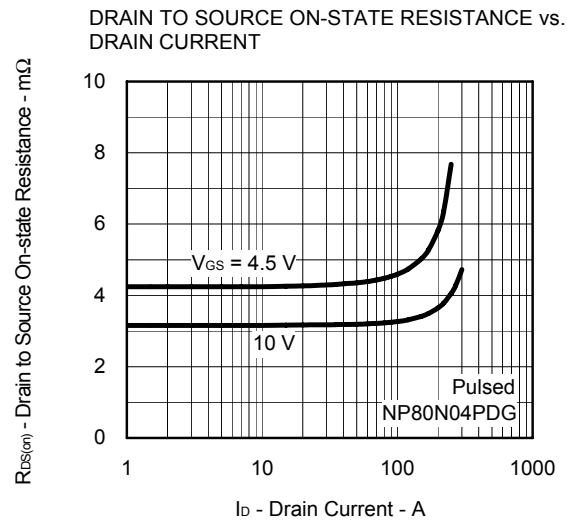
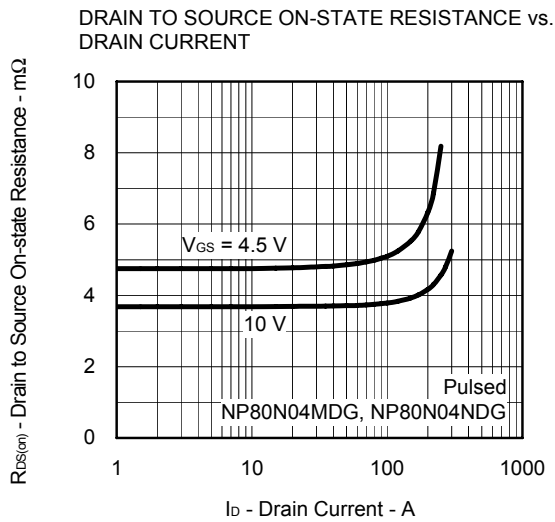


GATE TO SOURCE THRESHOLD VOLTAGE vs. CHANNEL TEMPERATURE

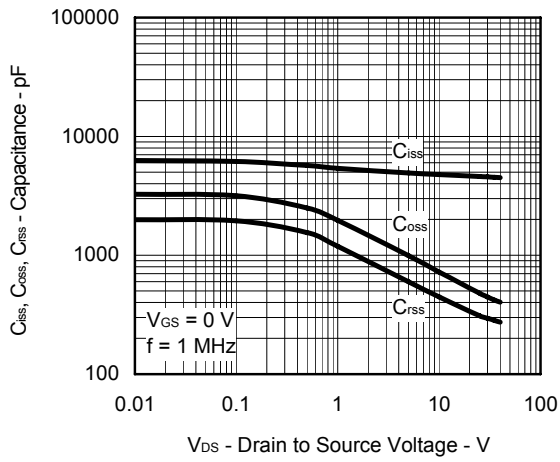


FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT

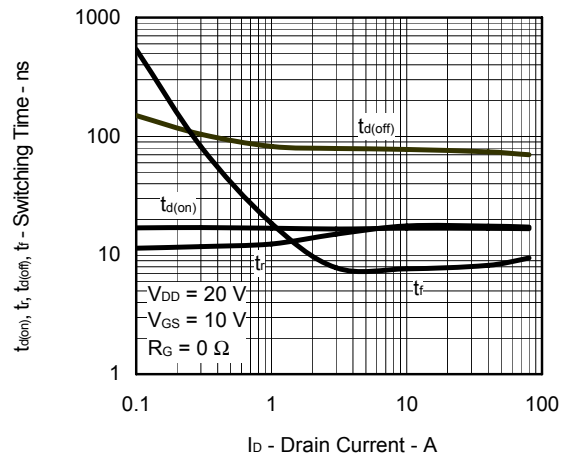




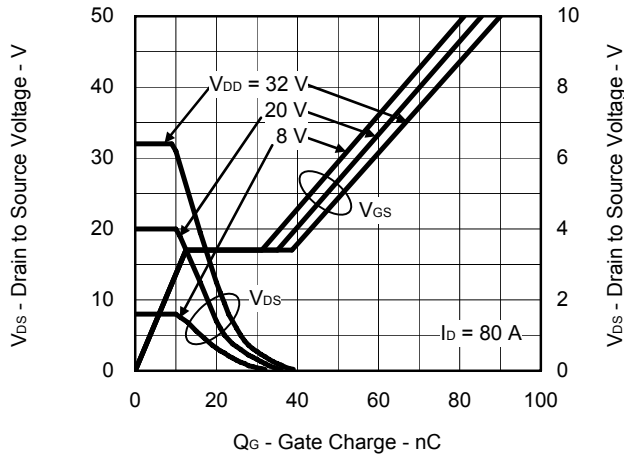
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



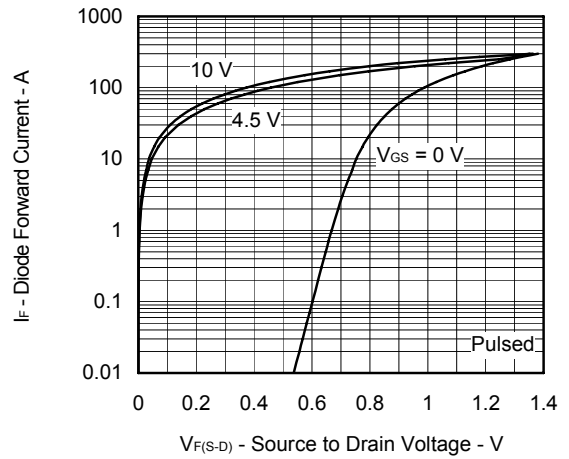
SWITCHING CHARACTERISTICS



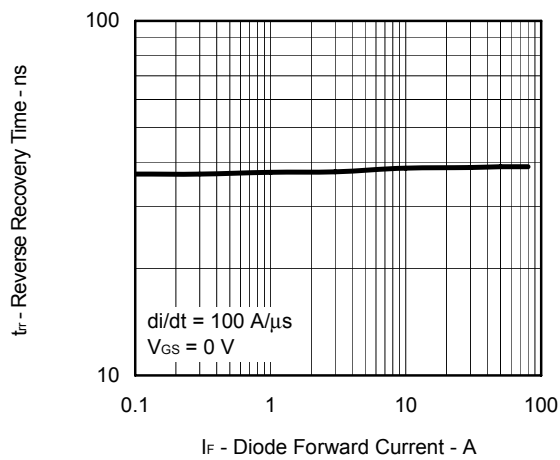
DYNAMIC INPUT/OUTPUT CHARACTERISTICS



SOURCE TO DRAIN DIODE FORWARD VOLTAGE

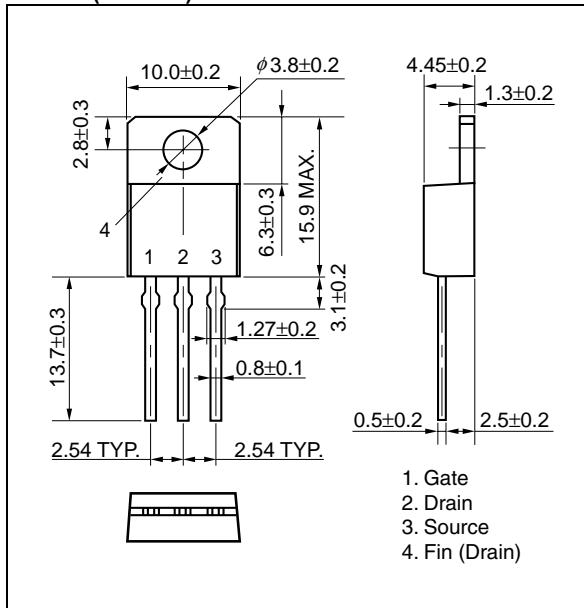


REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT

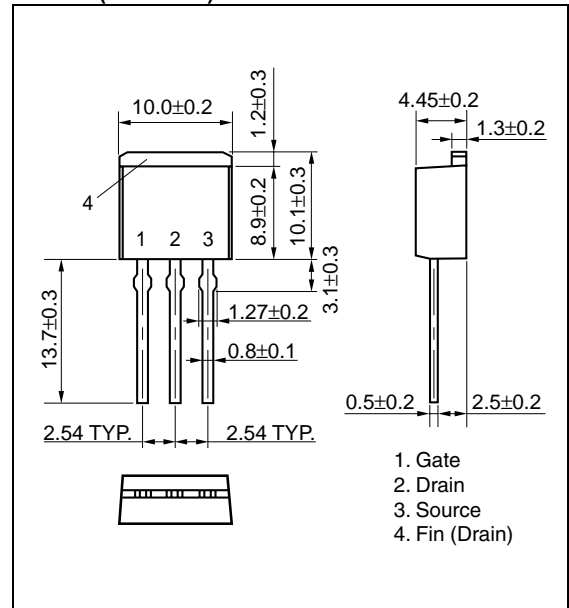


PACKAGE DRAWINGS (Unit: mm)

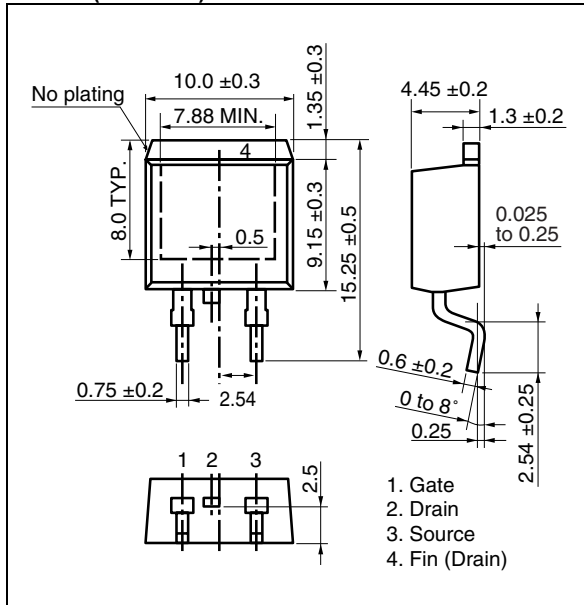
TO-220 (MP-25K)



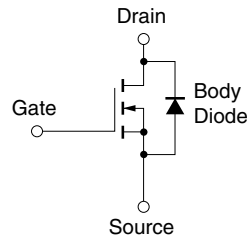
TO-262 (MP-25SK)



TO-263 (MP-25ZP)



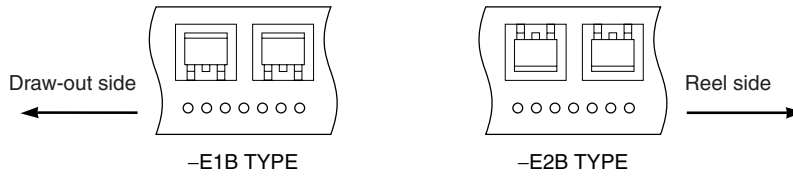
EQUIVALENT CIRCUIT



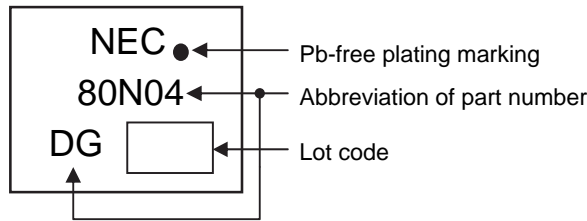
Remark Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

TAPE INFORMATION (NP80N04PDG)

There are two types (-E1B, -E2B) of taping depending on the direction of the device.



MARKING INFORMATION



RECOMMENDED SOLDERING CONDITIONS

These products should be soldered and mounted under the following recommended conditions.

For soldering methods and conditions other than those recommended below, please contact an NEC Electronics sales representative.

For technical information, see the following website.

Semiconductor Device Mount Manual (<http://www.necel.com/pkg/en/mount/index.html>)

Soldering Method	Soldering Conditions	Recommended Condition Symbol
Infrared reflow NP80N04PDG	Maximum temperature (Package's surface temperature): 260°C or below Time at maximum temperature: 10 seconds or less Time of temperature higher than 220°C: 60 seconds or less Preheating time at 160 to 180°C: 60 to 120 seconds Maximum number of reflow processes: 3 times Maximum chlorine content of rosin flux (percentage mass): 0.2% or less	IR60-00-3
Wave soldering NP80N04MDG, NP80N04NDG	Maximum temperature (Solder temperature): 260°C or below Time: 10 seconds or less Maximum chlorine content of rosin flux: 0.2% (wt.) or less	THDWS
Partial heating NP80N04MDG, NP80N04NDG, NP80N04PDG	Maximum temperature (Pin temperature): 350°C or below Time (per side of the device): 3 seconds or less Maximum chlorine content of rosin flux: 0.2% (wt.) or less	P350

Caution Do not use different soldering methods together (except for partial heating).

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"Special": Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support).

"Specific": Aircraft, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems and medical equipment for life support, etc.

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